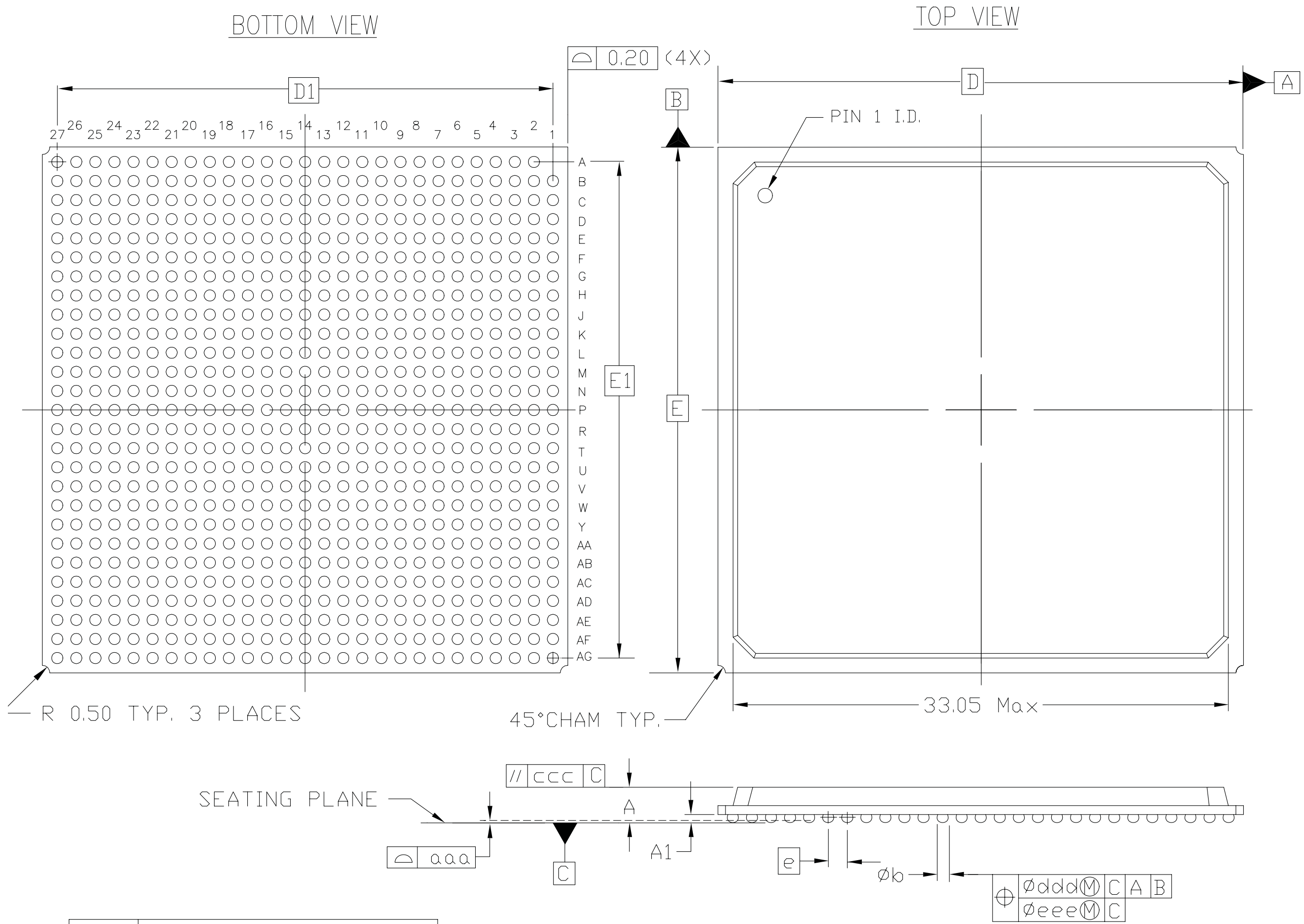
Molded BGA (BG728/BGG728) Package



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	—	2.33	2.60
A_1	0.50	0.60	0.70
D/E	35.00 BSC		
D_1/E_1	33.02 REF		
e	1.27BSC		
Øb	0.60	0.75	0.90
aaa	—	—	0.20
ccc	—	—	0.35
ddd	—	—	0.30
eee	—	—	0.15
M	27		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-BAR-1
4. NO SOLDER BALL AND LAND ON A1.

728-BALL MOLDED BGA (BG728/BGG728)

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/06/01	1.0	Initial Xilinx release.
04/13/06	1.1	Updated to include PB-free package.